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LCD EMI Filter Array with ESD Protection

Description

ON Semiconductor's CM1405 is an EMI filter array with ESD protection, which integrates eight Pi– filters (C–R–C). The CM1405 has component values of 25 pF – 100 Ω – 25 pF. The parts include avalanche–type ESD diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of ±30 kV, exceeding the maximum requirement of the IEC61000–4–2 international standard. Using the MIL–STD–883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than ±30 kV.

This device is particularly well-suited for portable electronics (e.g. mobile handsets, PDAs, notebook computers) because of its small package and easy-to-use pin assignments. In particular, the CM1405 is ideal for EMI filtering and protecting data lines from ESD for the LCD display in mobile handsets.

The CM1405–03 incorporates $OptiGuard^{\text{TM}}$ coating which results in improved reliability at assembly and is available in a space–saving, low–profile Chip Scale Package with RoHS compliant lead–free finishing.

Features

- Eight Channels of EMI Filtering
- ±30 kV ESD Protection on Each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- ±30 kV ESD Protection on Each Channel (HBM)
- Better than 35 dB of Attenuation at 800–2700 MHz
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum Filter and ESD Performance
- 20-Bump, 4.000 mm x 1.458 mm Footprint Chip Scale Package
- *OptiGuard*[™] Coated Version Available for Improved Reliability at Assembly
- These Devices are Pb-Free and are RoHS Compliant

Applications

- LCD Data Lines in Mobile Handsets
- EMI Filtering & ESD Protection for High-Speed I/O Ports
- EMI Filtering for High–Speed Data Lines
- Wireless Handsets
- Cell Phones
- Notebook Computers
- PDAs / Handheld PCs



ON Semiconductor®

http://onsemi.com



WLCSP20 CP SUFFIX CASE 567BZ

MARKING DIAGRAM

| N051 | N053 | |
|--------------------------------|----------------------------------|--|
| CM1405–01 -Bump CSP Package | CM1405-03 20-Bump CSP Package | |
| N051 = CM1405-01CP | | |

= CM1405-03CP

20-

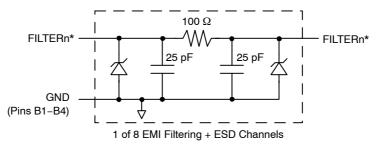
ORDERING INFORMATION

N053

| Device | Package | Shipping [†] |
|-------------|---------------------|-----------------------|
| CM1405-01CP | CSP-20 (Pb-Free) | 3500/Tape & Reel |
| CM1405-03CP | CSP-20 (Pb-Free) | 3500/Tape & Reel |

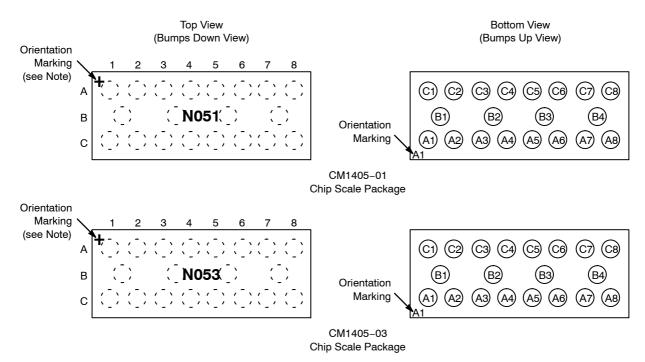
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

BLOCK DIAGRAM



*See Package/Pinout Diagrams for expanded pin information.

PACKAGE / PINOUT DIAGRAMS



Note: Lead-free devices are specified by using a "+" character for the top side orientation mark.

Table 1. PIN DESCRIPTIONS

| Pins | Name | Description | Pins | Name | Description |
|-------|---------|------------------|------|---------|------------------|
| A1 | FILTER1 | Filter Channel 1 | C1 | FILTER1 | Filter Channel 1 |
| A2 | FILTER2 | Filter Channel 2 | C2 | FILTER2 | Filter Channel 2 |
| A3 | FILTER3 | Filter Channel 3 | C3 | FILTER3 | Filter Channel 3 |
| A4 | FILTER4 | Filter Channel 4 | C4 | FILTER4 | Filter Channel 4 |
| A5 | FILTER5 | Filter Channel 5 | C5 | FILTER5 | Filter Channel 5 |
| A6 | FILTER6 | Filter Channel 6 | C6 | FILTER6 | Filter Channel 6 |
| A7 | FILTER7 | Filter Channel 7 | C7 | FILTER7 | Filter Channel 7 |
| A8 | FILTER8 | Filter Channel 8 | C8 | FILTER8 | Filter Channel 8 |
| B1-B4 | GND | Device Ground | | | |

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

| Parameter | Rating | Units |
|---------------------------|-------------|-------|
| Storage Temperature Range | -65 to +150 | °C |
| DC Power per Resistor | 100 | mW |
| DC Package Power Rating | 500 | mW |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

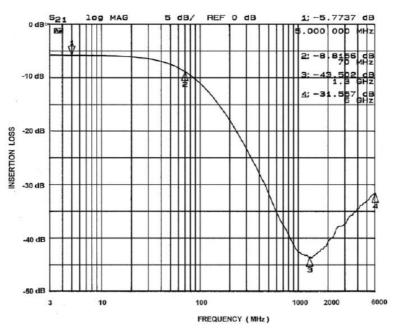
| Parameter | Rating | Units |
|-----------------------------|------------|-------|
| Operating Temperature Range | -40 to +85 | °C |

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

| Symbol | Parameter | Conditions | Min | Тур | Max | Units |
|--------------------|--|---|-------------|-------------|-------------|-------|
| R | Resistance | | 80 | 100 | 120 | Ω |
| С | Capacitance | At 2.5 V DC, 1 MHz, 30 mV AC | 20 | 25 | 30 | pF |
| V _{DIODE} | Diode Standoff Voltage | I _{DIODE} = 10 μA | | 6.0 | | V |
| I _{LEAK} | Diode Leakage Current (reverse bias) | V _{DIODE} = +3.3 V | | 0.1 | 1 | μA |
| V _{SIG} | Signal Clamp Voltage Positive Clamp Negative Clamp | $I_{LOAD} = 10 \text{ mA}$ $I_{LOAD} = -10 \text{ mA}$ | 5.6 -1.5 | 6.8 -0.8 | 9.0 -0.4 | V |
| V _{ESD} | In-system ESD Withstand Voltage a) Human Body Model, MIL-STD-883, Method 3015 b) Contact Discharge per IEC 61000-4-2 Level 4 | (Note 2) | 30 30 | | | kV |
| R _{DYN} | Dynamic Resistance Positive Negative | | | 1.5 0.9 | | Ω |
| f _C | Cut–off Frequency $Z_{SOURCE} = 50 \Omega$, $Z_{LOAD} = 50 \Omega$ | R = 100 Ω, C = 25 pF | | 70 | | MHz |

1. $T_A = 25$ °C unless otherwise specified. 2. ESD applied to input and output pins with respect to GND, one at a time.

PERFORMANCE INFORMATION





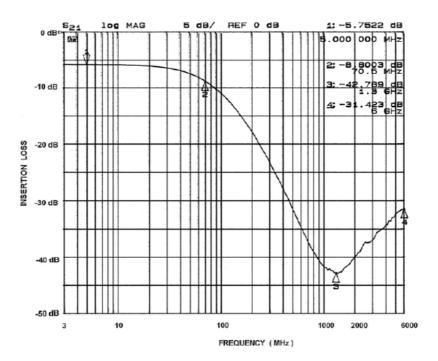
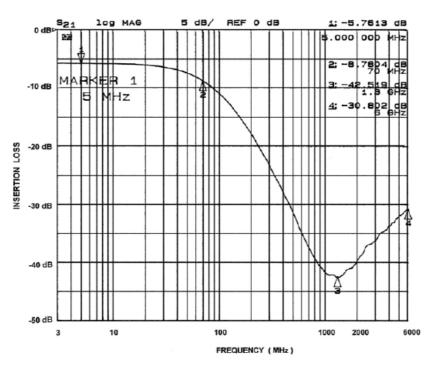
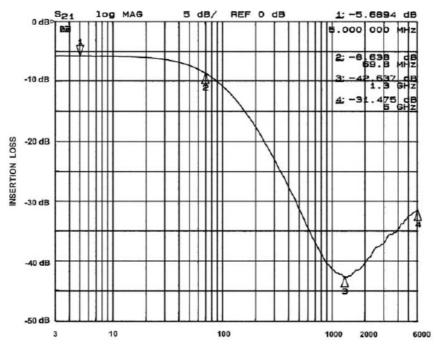


Figure 2. A2–C2 EMI Filter Performance

PERFORMANCE INFORMATION (Cont'd)

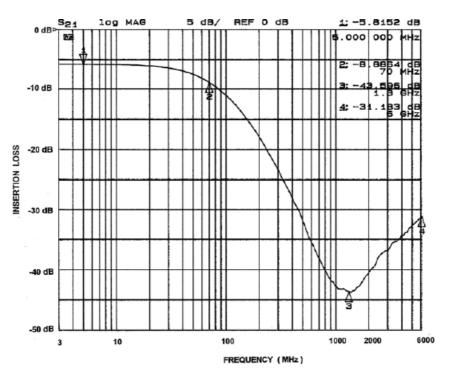








PERFORMANCE INFORMATION (Cont'd)





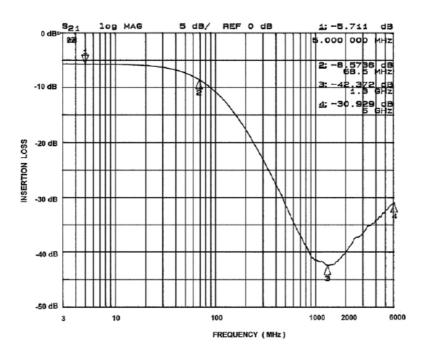
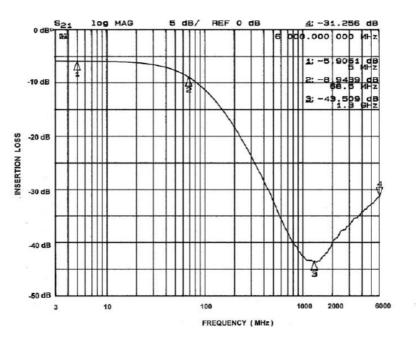
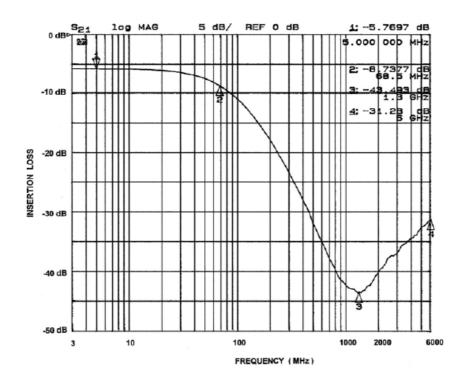


Figure 6. A6–C6 EMI Filter Performance

PERFORMANCE INFORMATION (Cont'd)









PERFORMANCE INFORMATION (Cont'd)

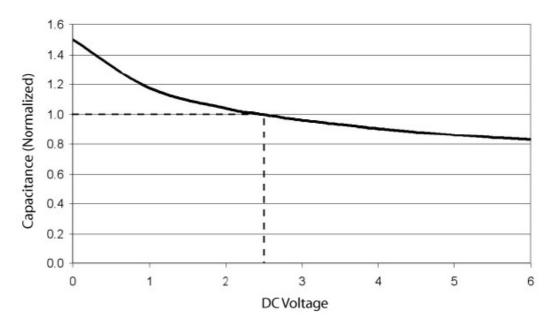
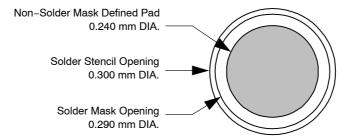


Figure 9. Filter Capacitance vs. Input Voltage over Temperature (normalized to capacitance at 2.5 VDC and 25°C)

APPLICATION INFORMATION

Table 5. PRINTED CIRCUIT BOARD RECOMMENDATIONS

| Parameter | Value | | |
|--|------------------------------|--|--|
| Pad Size on PCB | 0.240 mm | | |
| Pad Shape | Round | | |
| Pad Definition | Non-Solder Mask defined pads | | |
| Solder Mask Opening | 0.290 mm Round | | |
| Solder Stencil Thickness | 0.125 – 0.150 mm | | |
| Solder Stencil Aperture Opening (laser cut, 5% tapered walls) | 0.300 mm Round | | |
| Solder Flux Ratio | 50/50 by volume | | |
| Solder Paste Type | No Clean | | |
| Pad Protective Finish | OSP (Entek Cu Plus 106A) | | |
| Tolerance – Edge To Corner Ball | ±50 μm | | |
| Solder Ball Side Coplanarity | ±20 μm | | |
| Maximum Dwell Time Above Liquidous (183°C) | 60 seconds | | |
| Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste | 260°C | | |





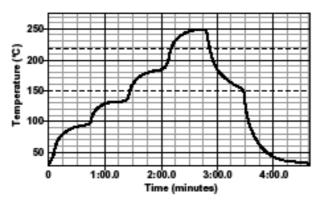
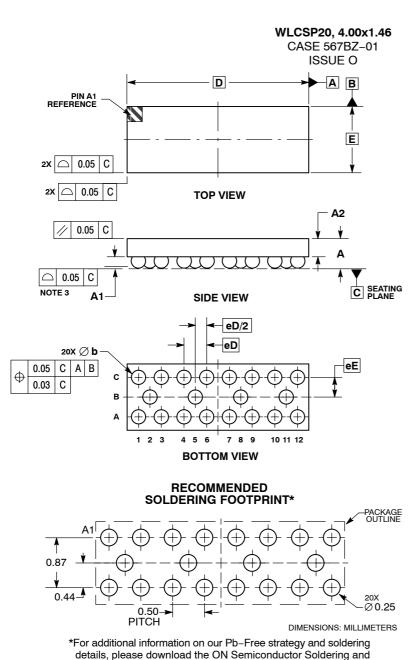


Figure 11. Lead-free (SnAgCu) Solder Ball Reflow Profile

PACKAGE DIMENSIONS



NOTES

1. DIMENSIONING AND TOLERANCING PER

ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS. 2 З.

| CHOWING OF SOLDLIN | | | |
|--------------------|----------------------------------|------|--|
| | MILLIMETERS | | |
| DIM | MIN | MAX | |
| Α | 0.56 | 0.65 | |
| A1 | 0.21 | 0.27 | |
| A2 | 0.40 REF | | |
| b | 0.29 | 0.35 | |
| D | 4.00 BSC 1.46 BSC 0.50 BSC | | |
| Е | | | |
| eD | | | |
| еE | 0.435 BSC | | |

Mounting Techniques Reference Manual, SOLDERRM/D.

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